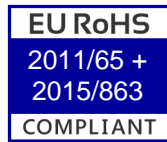


E1SDA12-25.000M TR
[Click part number to visit Part Number Details page](#)
REGULATORY COMPLIANCE (Data Sheet downloaded on Dec 15, 2019)
[Click badges to download compliance docs](#)

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.

**ITEM DESCRIPTION**

Quartz Crystal Resonator HC49/UP Short 2 Pad Surface Mount (SMD) 3.2mm Height Metal Resistance Weld Seal 25.000MHz ± 30 ppm at 25°C, ± 50 ppm over 0°C to +70°C 12pF Parallel Resonant

ELECTRICAL SPECIFICATIONS

| | |
|-------------------------------|--|
| Nominal Frequency | 25.000MHz |
| Frequency Tolerance/Stability | ± 30 ppm at 25°C, ± 50 ppm over 0°C to +70°C |
| Aging at 25°C | ± 5 ppm/year Maximum |
| Load Capacitance | 12pF Parallel Resonant |
| Shunt Capacitance | 7pF Maximum |
| Equivalent Series Resistance | 40 Ohms Maximum |
| Mode of Operation | AT-Cut Fundamental |
| Drive Level | 1mWatt Maximum |
| Storage Temperature Range | -55°C to +125°C |
| Insulation Resistance | 500 Megaohms Minimum (Measured at 100Vdc) |

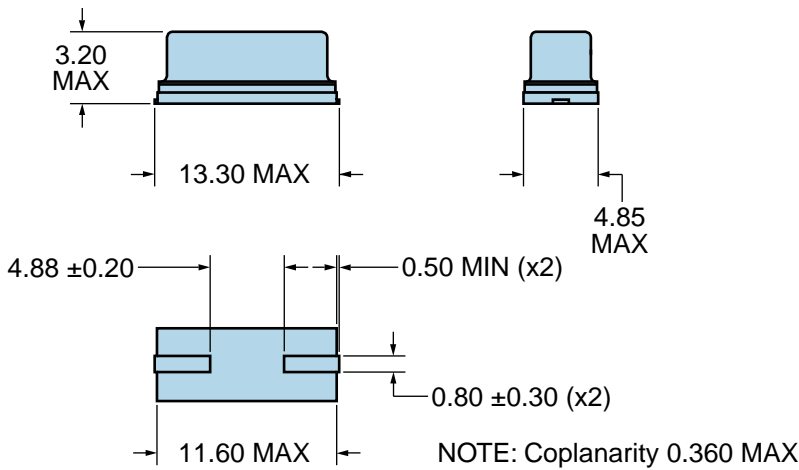
ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

| | |
|------------------------------|---|
| ESD Susceptibility | MIL-STD-883, Method 3015, Class 1, HBM: 1500V |
| Fine Leak Test | MIL-STD-883, Method 1014, Condition A |
| Flammability | UL94-V0 |
| Gross Leak Test | MIL-STD-883, Method 1014, Condition C |
| Mechanical Shock | MIL-STD-202, Method 213, Condition C |
| Moisture Resistance | MIL-STD-883, Method 1004 |
| Moisture Sensitivity | J-STD-020, MSL1 |
| Resistance to Soldering Heat | MIL-STD-202, Method 210, Condition K |
| Resistance to Solvents | MIL-STD-202, Method 215 |
| Solderability | MIL-STD-883, Method 2003 |
| Temperature Cycling | MIL-STD-883, Method 1010, Condition B |
| Vibration | MIL-STD-883, Method 2007, Condition A |

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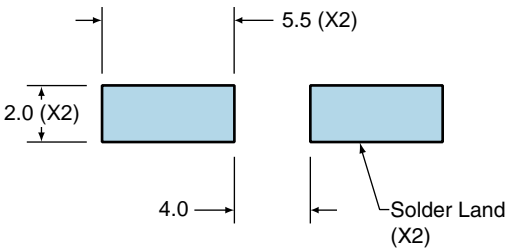
MECHANICAL DIMENSIONS (all dimensions in millimeters)



| LINE | MARKING |
|------|--|
| 1 | E25.000M E=Ecliptek Designator |

Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

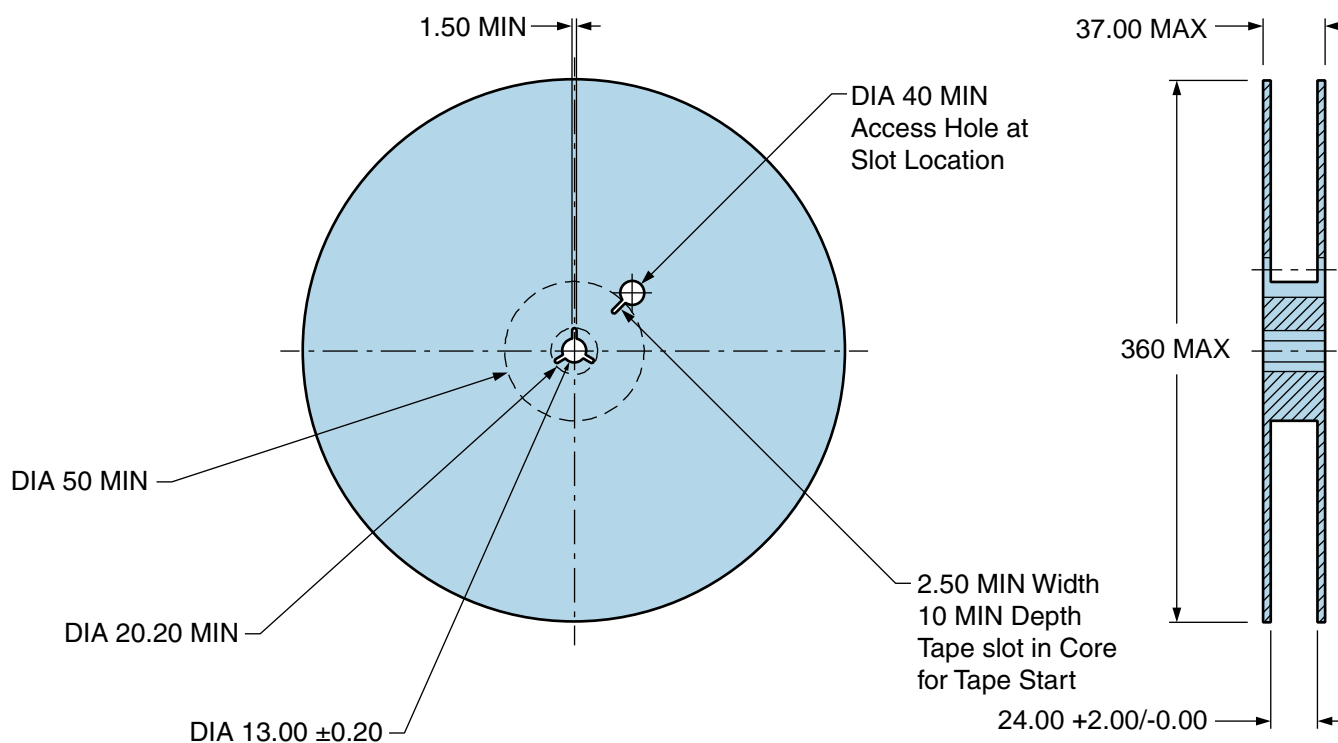
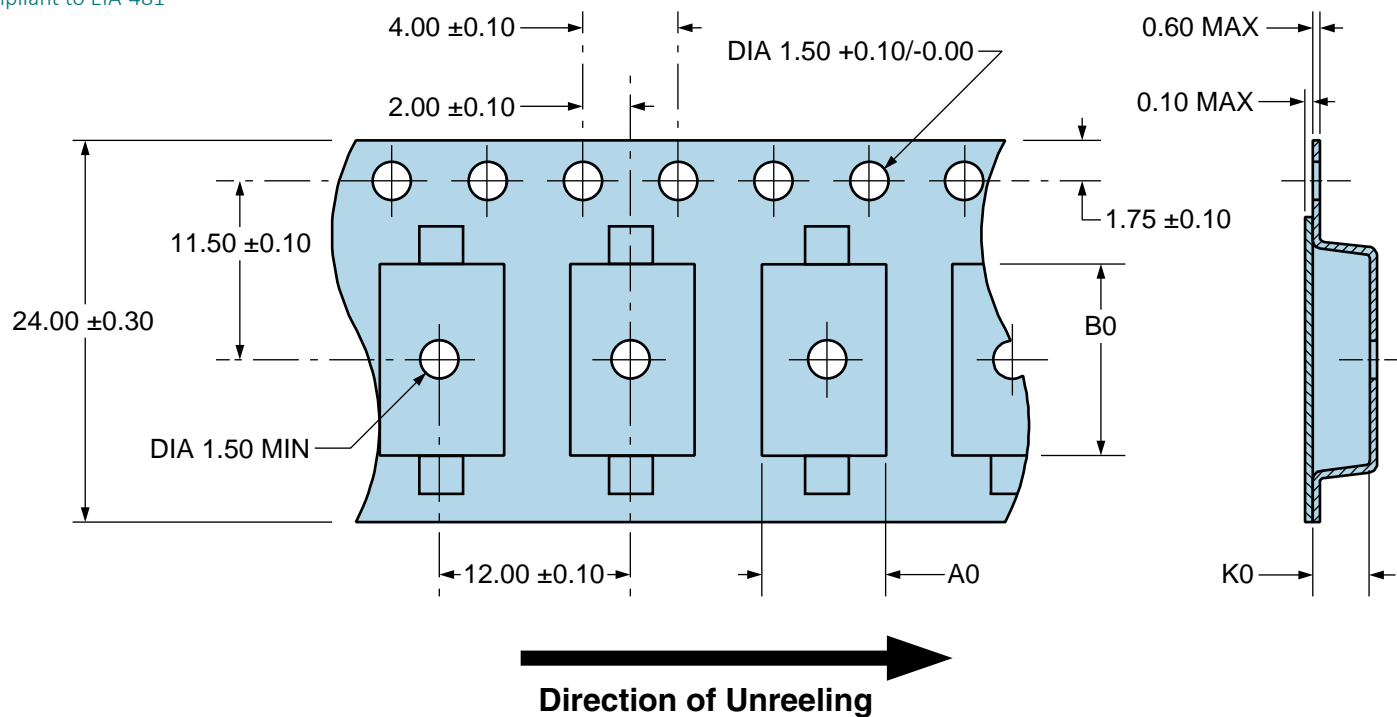
E1SDA12-25.000M TR

Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

All Dimensions in Millimeters

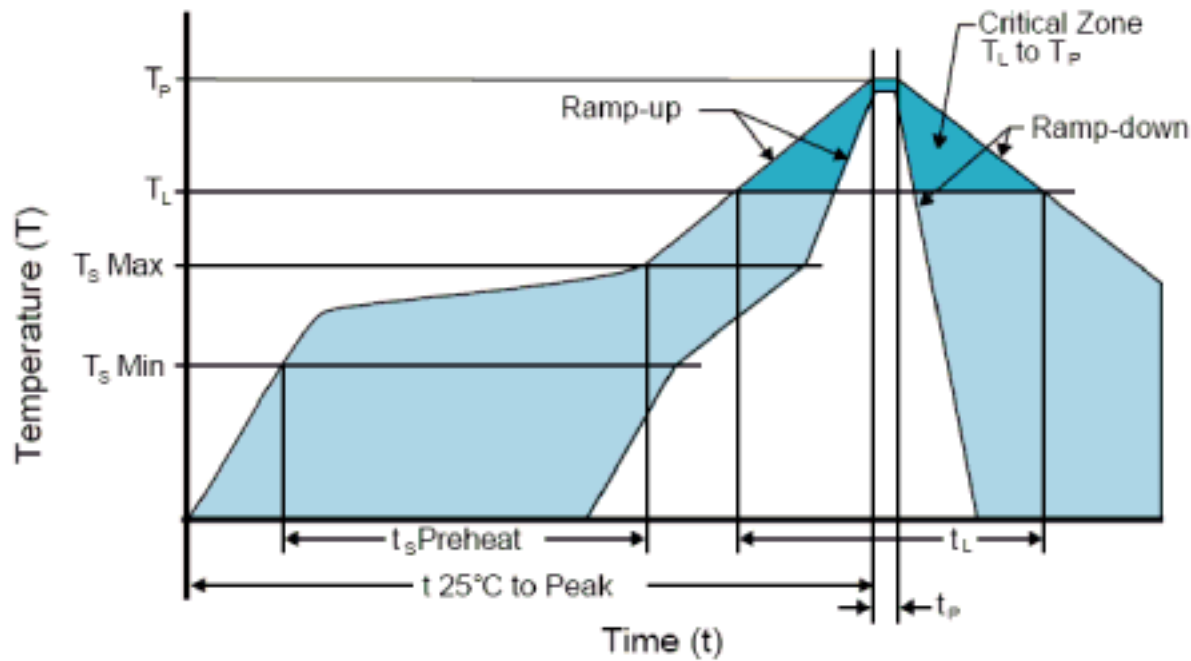
Compliant to EIA-481



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Recommended Solder Reflow Methods



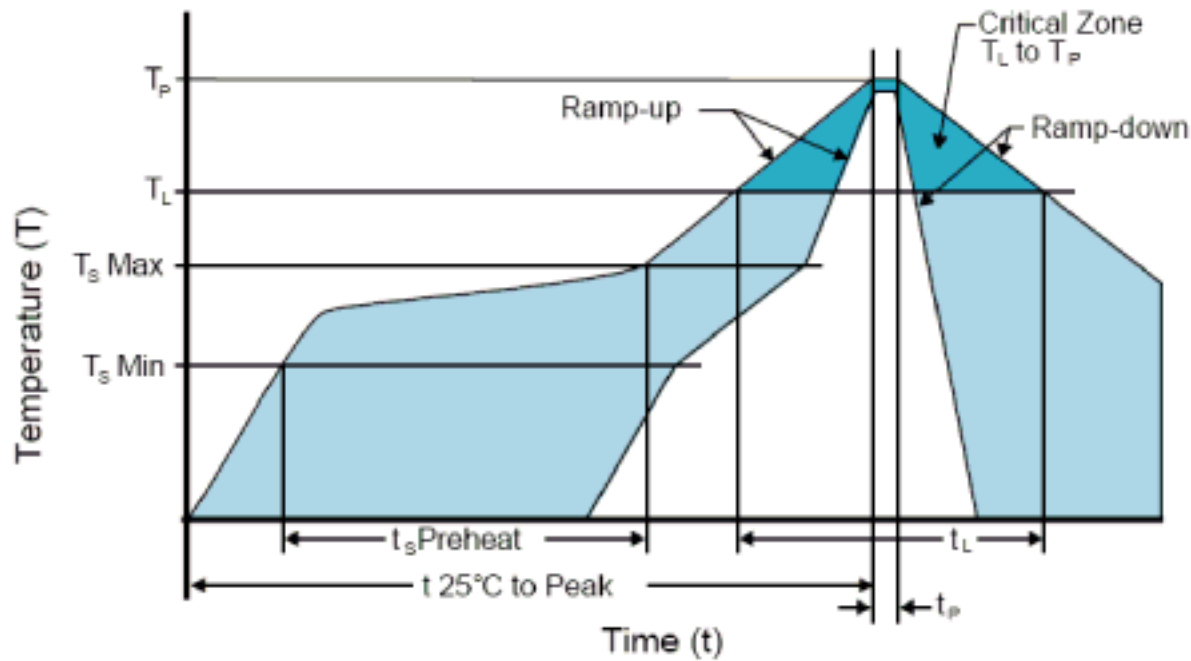
High Temperature Infrared/Convection

| | |
|-------------------------------------|---|
| Ts MAX to TL (Ramp-up Rate) | 3°C/Second Maximum |
| Preheat | |
| - Temperature Minimum (Ts MIN) | 150°C |
| - Temperature Typical (Ts TYP) | 175°C |
| - Temperature Maximum (Ts MAX) | 200°C |
| - Time (ts MIN) | 60 - 180 Seconds |
| Ramp-up Rate (TL to TP) | 3°C/Second Maximum |
| Time Maintained Above: | |
| - Temperature (TL) | 217°C |
| - Time (tL) | 60 - 150 Seconds |
| Peak Temperature (TP) | 260°C Maximum for 10 Seconds Maximum |
| Target Peak Temperature (TP Target) | 250°C +0/-5°C |
| Time within 5°C of actual peak (tp) | 20 - 40 Seconds |
| Ramp-down Rate | 6°C/Second Maximum |
| Time 25°C to Peak Temperature (t) | 8 Minutes Maximum |
| Moisture Sensitivity Level | Level 1 |
| Additional Notes | Temperatures shown are applied to body of device. |

E1SDA12-25.000M TR

[Click part number to visit Part Number Details page](#)

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 245°C

| | |
|-------------------------------------|--|
| TS MAX to TL (Ramp-up Rate) | 5°C/Second Maximum |
| Preheat | |
| - Temperature Minimum (TS MIN) | N/A |
| - Temperature Typical (TS TYP) | 150°C |
| - Temperature Maximum (TS MAX) | N/A |
| - Time (ts MIN) | 30 - 60 Seconds |
| Ramp-up Rate (TL to TP) | 5°C/Second Maximum |
| Time Maintained Above: | |
| - Temperature (TL) | 150°C |
| - Time (tL) | 200 Seconds Maximum |
| Peak Temperature (TP) | 245°C Maximum |
| Target Peak Temperature (TP Target) | 245°C Maximum 2 Times / 230°C Maximum 1 Time |
| Time within 5°C of actual peak (tP) | 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time |
| Ramp-down Rate | 5°C/Second Maximum |
| Time 25°C to Peak Temperature (t) | N/A |
| Moisture Sensitivity Level | Level 1 |
| Additional Notes | Temperatures shown are applied to body of device. |

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)